HMC218MS8 / 218MS8E

v04.0906

GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 6 GHz

Typical Applications

The HMC218MS8 / HMC218MS8E is ideal for:

- Basestations, Repeaters & Access Points
- WiMAX, WiBro & Fixed Wireless
- Portables & Subscribers
- PLMR, Public Safety & Telematics

Features

Passive Double-Balanced Topology

Input IP3 : +18 dBm

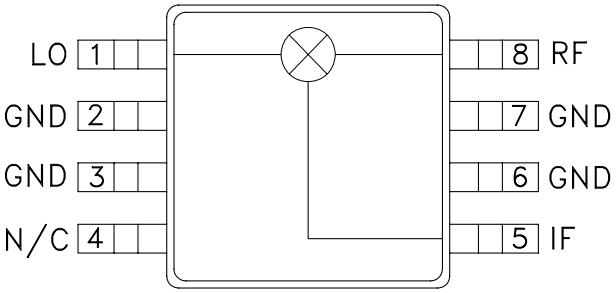
Low Conversion Loss: 6.5 dB

LO / RF Isolation: 30 dB

LO / IF Isolation: 25 dB

Upconverter & Downconverter Applications

Functional Diagram



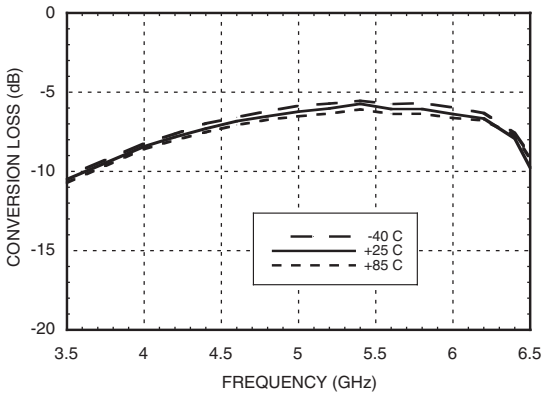
General Description

The HMC218MS8 & HMC218MS8E are ultra miniature double-balanced mixers in 8 lead plastic surface mount packages (MSOP). This passive MMIC mixer is constructed of GaAs Schottky diodes and novel planar transformer baluns on the chip. The device can be used as an upconverter, downconverter, bi-phase modulator / demodulator, or phase comparator. The low conversion loss, high isolation and wide IF bandwidth make this mixer ideal for a variety of Rx and Tx frequency plans.

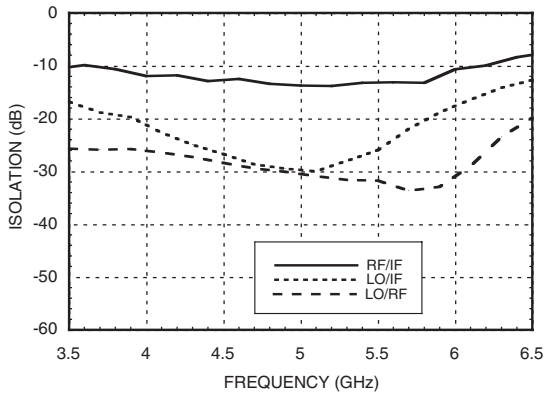
Electrical Specifications, T_A = +25° C, As a Function of LO Drive

Parameter	LO = +13 dBm IF = 100 MHz			LO = +10 dBm IF = 100 MHz			LO = +7 dBm IF = 100 MHz			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency Range, RF & LO	4.5 - 6.0			4.5 - 6.0			4.7 - 5.9			GHz
Frequency Range, IF	DC - 1.6			DC - 1.6			DC - 1.5			GHz
Conversion Loss		6.5	8.5		8	9.5		8	9.5	dB
Noise Figure (SSB)		6.5	8.5		8	9.5		8	9.5	dB
LO to RF Isolation	25	30		25	30		23	28		dB
LO to IF Isolation	15	25		14	25		12	23		dB
IP3 (Input) 5.2 GHz 5.8 GHz	12 15	16 18		11 13	14 17		9 10	12 13		dBm
1 dB Gain Compression (Input)	7	10		5	9		4	7		dBm

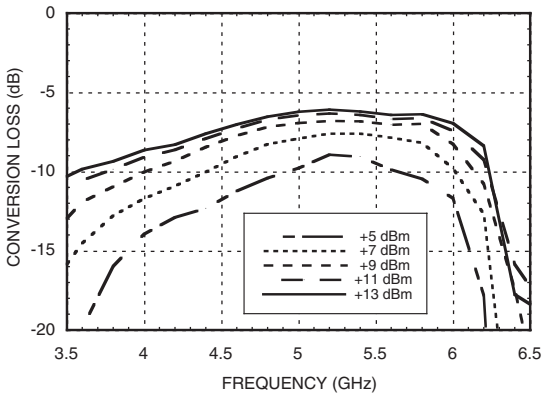
Conversion Loss vs. Temperature @ LO = +13 dBm



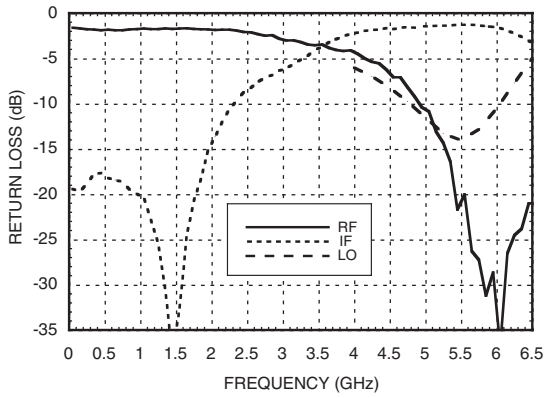
Isolation @ LO = +13 dBm



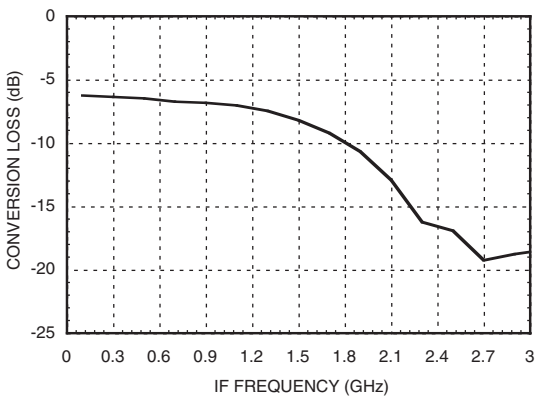
Conversion Loss vs. LO Drive



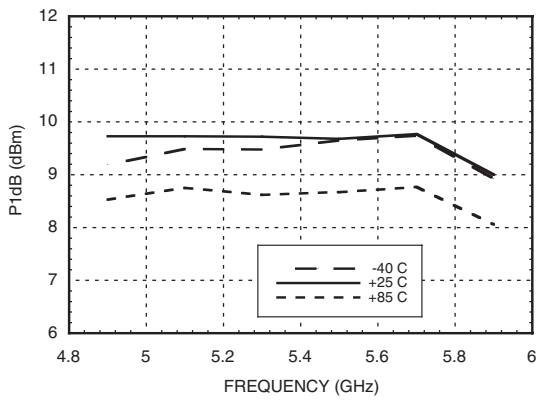
Return Loss @ LO = +13 dBm



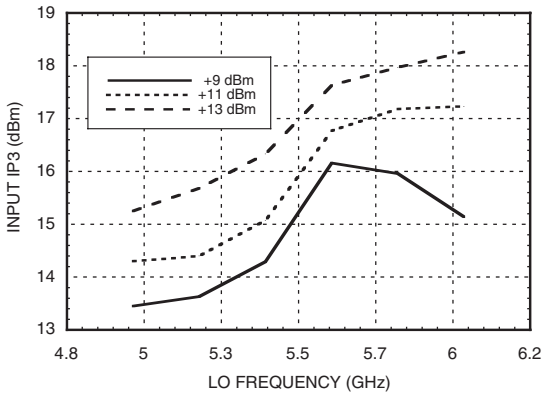
IF Bandwidth @ LO = +13 dBm



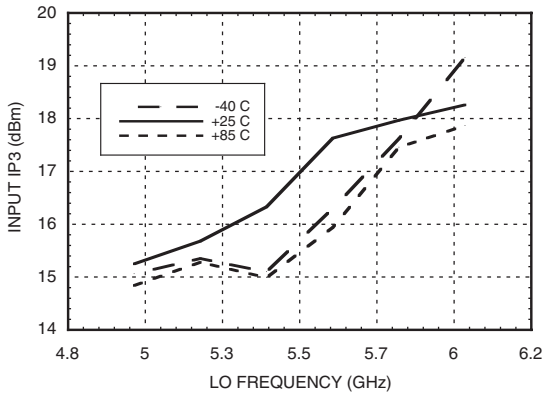
P1dB vs. Temperature LO = +13 dBm



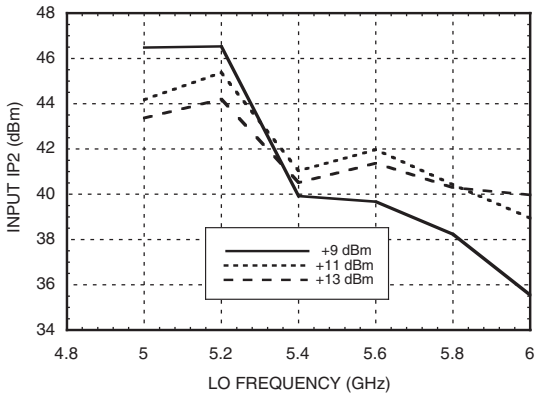
Input IP3 vs. LO Drive



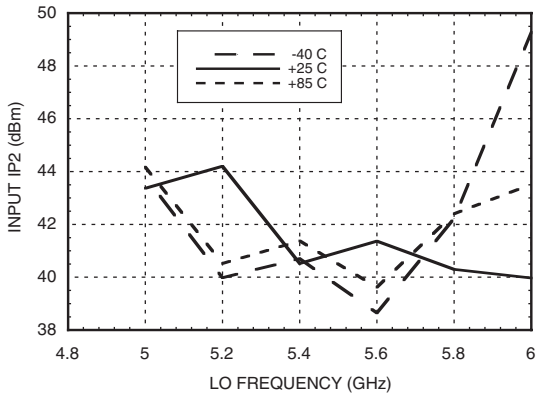
Input IP3 vs. Temperature @ LO = +13 dBm



Input IP2 vs. LO Drive



Input IP2 vs. Temperature @ LO = +13 dBm



MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	xx	0	15	23	36
1	10	0	34	27	59
2	67	61	56	59	68
3	97	82	81	60	77
4	>105	>105	>105	>105	96

RF = 5.15 GHz @ -10 dBm
LO = 5.25 GHz @ +13 dBm
All values in dBc relative to the IF

Harmonics of LO

LO Freq. (GHz)	nLO Spur at RF Port			
	1	2	3	4
5.0	31	30	57	68
5.2	31	32	59	69
5.4	32	35	62	73
5.6	32	35	64	76
5.8	33	35	65	76
6.0	33	32	64	68

LO = +13 dBm
Values in dBc below input LO level measured at the RF port.

HMC218MS8 / 218MS8E

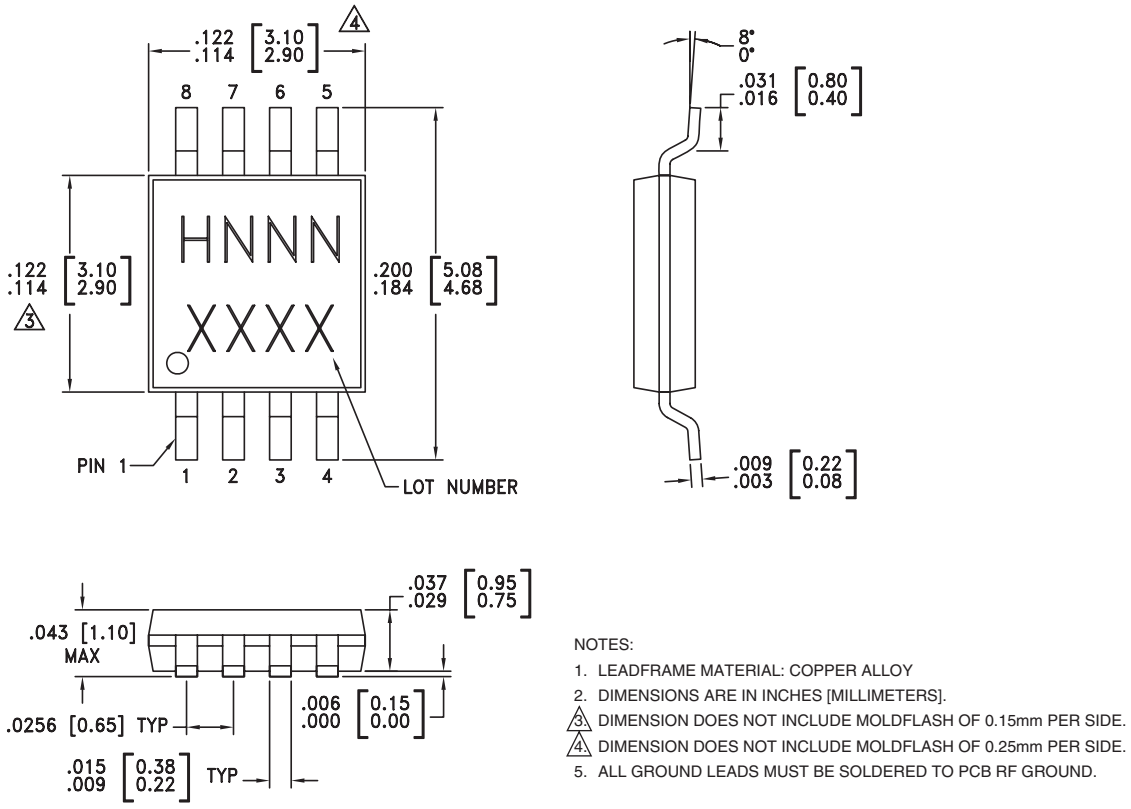
GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4.5 - 6 GHz

Absolute Maximum Ratings

RF / IF Input	+13 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



NOTES:

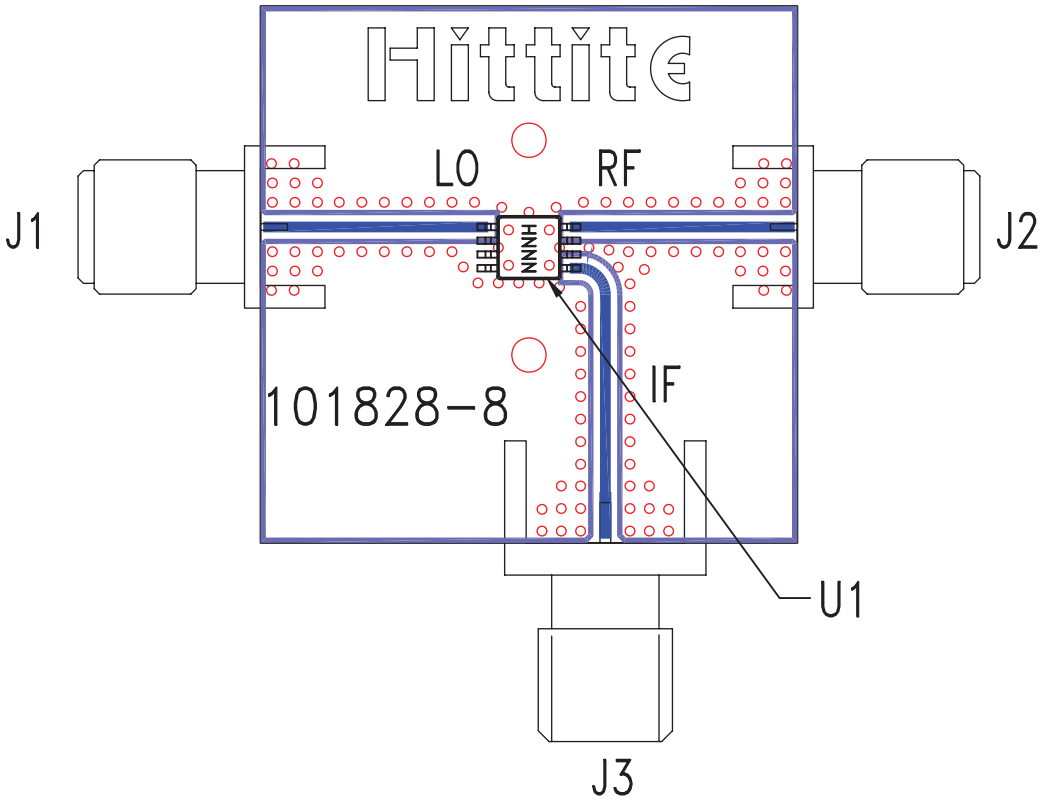
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC218MS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H218 XXXX
HMC218MS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H218 XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX

Evaluation Circuit Board



List of Materials for Evaluation PCB 101830 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC218MS8 / HMC218MS8E Mixer
PCB [2]	101828 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

Notes: